

## Features

- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- High Conductance
- **Lead, Halogen and Antimony Free, RoHS Compliant "Green" Device (Notes 3 and 4)**

## Mechanical Data

- Case: SOD-323
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.004 grams (approximate)



Top View

## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>R(RM)</sub>	20	V
Working Peak Reverse Voltage	V <sub>R(WM)</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	V
Average Rectified Output Current	I <sub>O</sub>	0.5	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	2	A

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P <sub>D</sub>	235	mW
Typical Thermal Resistance Junction to Ambient (Note 1)	R <sub>θJA</sub>	426	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +125	°C

## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	Test Conditions
Minimum Reverse Breakdown Voltage (Note 2)	V <sub>(BR)R</sub>	20	V	I <sub>R</sub> = 0.5mA
Maximum Forward Voltage Drop	V <sub>F</sub>	0.310	V	I <sub>F</sub> = 0.1A
		0.430		I <sub>F</sub> = 0.5A
Maximum Leakage Current (Note 2)	I <sub>R</sub>	100	μA	V <sub>R</sub> = 10V
		250		V <sub>R</sub> = 20V
Typical Total Capacitance	C <sub>T</sub>	58	pF	f = 1MHz, V <sub>R</sub> = 0VDC

- Notes:
1. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  2. Short duration pulse test used to minimize self-heating effect.
  3. No purposefully added lead. Halogen and Antimony Free.
  4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.

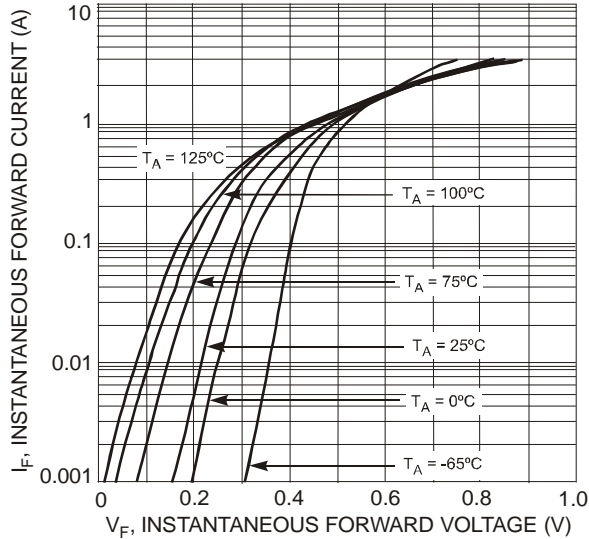


Fig. 1 Typical Forward Characteristics

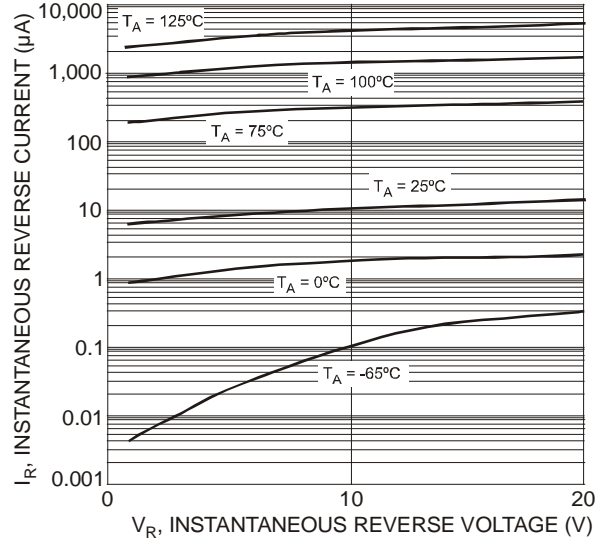


Fig. 2 Typical Reverse Characteristics

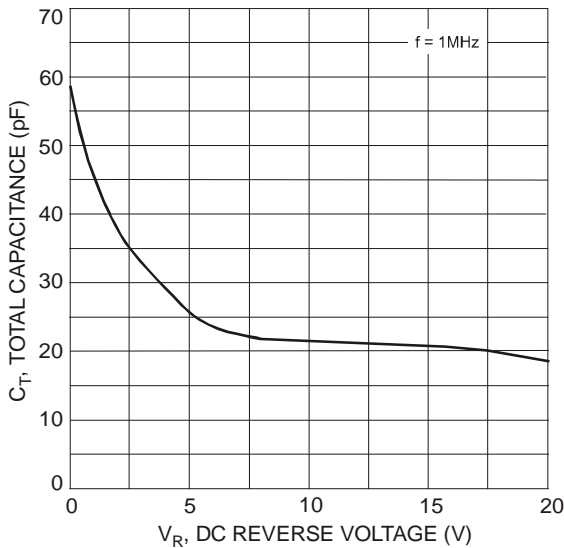


Fig. 3 Total Capacitance vs. Reverse Voltage

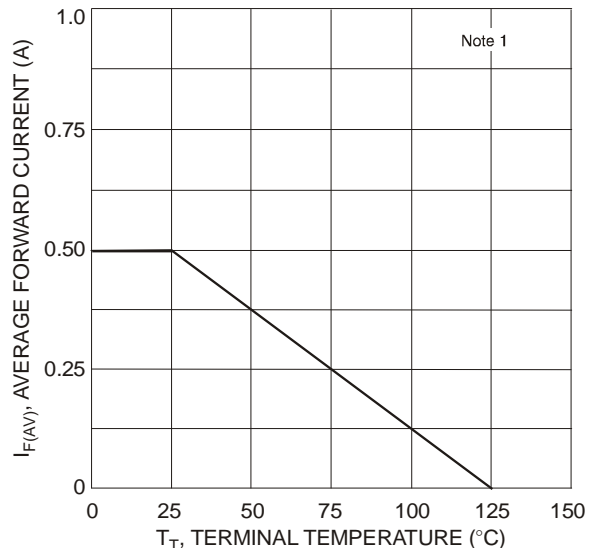


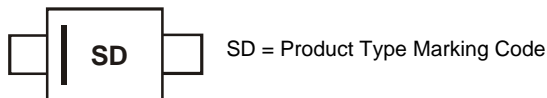
Fig. 4 Forward Current Derating Curve

**Ordering Information** (Note 5)

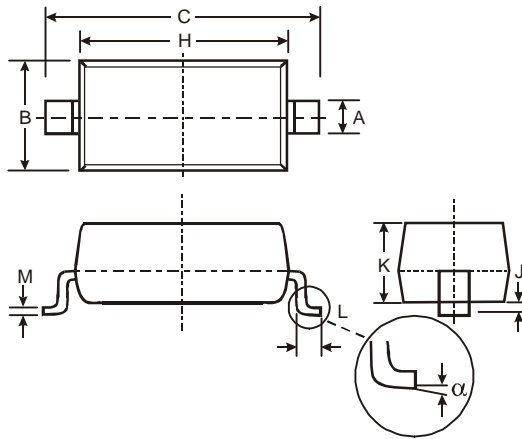
Part Number	Case	Packaging
B0520WS-7-F	SOD-323	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**

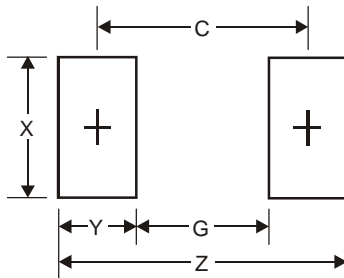


**Package Outline Dimensions**



SOD-323		
Dim	Min	Max
A	0.25	0.35
B	1.20	1.40
C	2.30	2.70
H	1.60	1.80
J	0.00	0.10
K	1.0	1.1
L	0.20	0.40
M	0.10	0.15
$\alpha$	0°	8°
All Dimensions in mm		

**Suggested Pad Layout**



Dimensions	Value (in mm)
Z	3.75
G	1.05
X	0.65
Y	1.35
C	2.40

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